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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM7®
Core Size	16/32-Bit
Speed	55MHz
Connectivity	CANbus, Ethernet, I²C, SPI, SSC, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	62
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128K x 8
Voltage - Supply (Vcc/Vdd)	1.65V ~ 1.95V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at91sam7xc512b-aur

- **Fully Static Operation: Up to 55 MHz at 1.65V and 85· C Worst Case Conditions**
- **Available in 100-lead LQFP Green and 100-ball TFBGA Green Packages**

1. Description

Atmel's AT91SAM7XC512/256/128 is a member of a series of highly integrated Flash microcontrollers based on the 32-bit ARM RISC processor. It features 512/256/128 Kbyte high-speed Flash and 128/64/32 Kbyte SRAM, a large set of peripherals, including an 802.3 Ethernet MAC, a CAN controller, an AES 128 Encryption accelerator and a Triple Data Encryption System. A complete set of system functions minimizes the number of external components.

The embedded Flash memory can be programmed in-system via the JTAG-ICE interface or via a parallel interface on a production programmer prior to mounting. Built-in lock bits and a security bit protect the firmware from accidental overwrite and preserve its confidentiality.

The AT91SAM7XC512/256/128 system controller includes a reset controller capable of managing the power-on sequence of the microcontroller and the complete system. Correct device operation can be monitored by a built-in brownout detector and a watchdog running off an integrated RC oscillator.

By combining the ARM7TDMI processor with on-chip Flash and SRAM, and a wide range of peripheral functions, including USART, SPI, CAN Controller, Ethernet MAC, AES 128 accelerator, TDES, Timer Counter, RTT and Analog-to-Digital Converters on a monolithic chip, the AT91SAM7XC512/256/128 is a powerful device that provides a flexible, cost-effective solution to many embedded control applications requiring secure communication over, for example, Ethernet, CAN wired and Zigbee™ wireless networks.

1.1 Configuration Summary of the AT91SAM7XC512/256/128

The AT91SAM7XC512, AT91SAM7XC256 and AT91SAM7XC128 differ only in memory sizes. Table 1-1 summarizes the configurations of the two devices.

Table 1-1. Configuration Summary

Device	Flash	Flash Organization	SRAM	AES	TDES
AT91SAM7XC512	512K bytes	dual plane	128K bytes	1 AES 256/192/128	1
AT91SAM7XC256	256K bytes	single plane	64K bytes	1 AES 128	1
AT91SAM7XC128	128K bytes	single plane	32K bytes	1 AES 128	1

4.2 100-lead LQFP Pinout

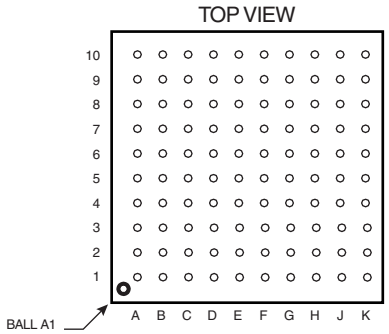
Table 4-1. Pinout in 100-lead LQFP Package

1	ADVREF	26	PA18/PGMD6	51	TDI	76	TDO
2	GND	27	PB9	52	GND	77	JTAGSEL
3	AD4	28	PB8	53	PB16	78	TMS
4	AD5	29	PB14	54	PB4	79	TCK
5	AD6	30	PB13	55	PA23/PGMD11	80	PA30
6	AD7	31	PB6	56	PA24/PGMD12	81	PA0/PGMEN0
7	VDDOUT	32	GND	57	NRST	82	PA1/PGMEN1
8	VDDIN	33	VDDIO	58	TST	83	GND
9	PB27/AD0	34	PB5	59	PA25/PGMD13	84	VDDIO
10	PB28/AD1	35	PB15	60	PA26/PGMD14	85	PA3
11	PB29/AD2	36	PB17	61	VDDIO	86	PA2
12	PB30/AD3	37	VDDCORE	62	VDDCORE	87	VDDCORE
13	PA8/PGMM0	38	PB7	63	PB18	88	PA4/PGMNCMD
14	PA9/PGMM1	39	PB12	64	PB19	89	PA5/PGMRDY
15	VDDCORE	40	PB0	65	PB20	90	PA6/PGMNOE
16	GND	41	PB1	66	PB21	91	PA7/PGMNVALID
17	VDDIO	42	PB2	67	PB22	92	ERASE
18	PA10/PGMM2	43	PB3	68	GND	93	DDM
19	PA11/PGMM3	44	PB10	69	PB23	94	DDP
20	PA12/PGMD0	45	PB11	70	PB24	95	VDDFLASH
21	PA13/PGMD1	46	PA19/PGMD7	71	PB25	96	GND
22	PA14/PGMD2	47	PA20/PGMD8	72	PB26	97	XIN/PGMCK
23	PA15/PGMD3	48	VDDIO	73	PA27/PGMD15	98	XOUT
24	PA16/PGMD4	49	PA21/PGMD9	74	PA28	99	PLLRC
25	PA17/PGMD5	50	PA22/PGMD10	75	PA29	100	VDDPLL

4.3 100-ball TFBGA Package Outline

Figure 4-2 shows the orientation of the 100-ball TFBGA package. A detailed mechanical description is given in the Mechanical Characteristics section of the full datasheet.

Figure 4-2. 100-ball TFBGA Package Orientation (Top View)



4.4 100-ball TFBGA Pinout

Table 4-2. Pinout in 100-ball TFBGA Package

Pin	Signal Name	Pin	Signal Name	Pin	Signal Name	Pin	Signal Name
A1	PA22/PGMD10	C6	PB17	F1	PB21	H6	PA7/PGMNVALID
A2	PA21/PGMD9	C7	PB13	F2	PB23	H7	PA9/PGMM1
A3	PA20/PGMD8	C8	PA13/PGMD1	F3	PB25	H8	PA8/PGMM0
A4	PB1	C9	PA12/PGMD0	F4	PB26	H9	PB29/AD2
A5	PB7	C10	PA15/PGMD3	F5	TCK	H10	PLLRC
A6	PB5	D1	PA23/PGMD11	F6	PA6/PGMNOE	J1	PA29
A7	PB8	D2	PA24/PGMD12	F7	ERASE	J2	PA30
A8	PB9	D3	NRST	F8	VDDCORE	J3	PA0/PGMEN0
A9	PA18/PGMD6	D4	TST	F9	GND	J4	PA1/PGMEN1
A10	VDDIO	D5	PB19	F10	VDDIN	J5	VDDFLASH
B1	TDI	D6	PB6	G1	PB22	J6	GND
B2	PA19/PGMD7	D7	PA10/PGMM2	G2	PB24	J7	XIN/PGMCK
B3	PB11	D8	VDDIO	G3	PA27/PGMD15	J8	XOUT
B4	PB2	D9	PB27/AD0	G4	TDO	J9	GND
B5	PB12	D10	PA11/PGMM3	G5	PA2	J10	VDDPLL
B6	PB15	E1	PA25/PGMD13	G6	PA5/PGMRDY	K1	VDDCORE
B7	PB14	E2	PA26/PGMD14	G7	VDDCORE	K2	VDDCORE
B8	PA14/PGMD2	E3	PB18	G8	GND	K3	DDP
B9	PA16/PGMD4	E4	PB20	G9	PB30/AD3	K4	DDM
B10	PA17/PGMD5	E5	TMS	G10	VDDOUT	K5	GND
C1	PB16	E6	GND	H1	VDDCORE	K6	AD7
C2	PB4	E7	VDDIO	H2	PA28	K7	AD6
C3	PB10	E8	PB28/AD1	H3	JTAGSEL	K8	AD5
C4	PB3	E9	VDDIO	H4	PA3	K9	AD4
C5	PB0	E10	GND	H5	PA4/PGMNCMD	K10	ADVREF

6. I/O Lines Considerations

6.1 JTAG Port Pins

TMS, TDI and TCK are schmitt trigger inputs and are not 5-V tolerant. TMS, TDI and TCK do not integrate a pull-up resistor.

TDO is an output, driven at up to VDDIO, and has no pull-up resistor.

The JTAGSEL pin is used to select the JTAG boundary scan when asserted at a high level. The JTAGSEL pin integrates a permanent pull-down resistor of about 15 kΩ.

To eliminate any risk of spuriously entering the JTAG boundary scan mode due to noise on JTAGSEL, it should be tied externally to GND if boundary scan is not used, or pulled down with an external low-value resistor (such as 1 kΩ).

6.2 Test Pin

The TST pin is used for manufacturing test or fast programming mode of the AT91SAM7XC512/256/128 when asserted high. The TST pin integrates a permanent pull-down resistor of about 15 kΩ to GND.

To eliminate any risk of entering the test mode due to noise on the TST pin, it should be tied to GND if the FFPI is not used, or pulled down with an external low-value resistor (such as 1 kΩ).

To enter fast programming mode, the TST pin and the PA0 and PA1 pins should be tied high and PA2 tied to low.

Driving the TST pin at a high level while PA0 or PA1 is driven at 0 leads to unpredictable results.

6.3 Reset Pin

The NRST pin is bidirectional with an open drain output buffer. It is handled by the on-chip reset controller and can be driven low to provide a reset signal to the external components or asserted low externally to reset the microcontroller. There is no constraint on the length of the reset pulse, and the reset controller can guarantee a minimum pulse length. This allows connection of a simple push-button on the NRST pin as system user reset, and the use of the signal NRST to reset all the components of the system.

The NRST pin integrates a permanent pull-up resistor to VDDIO.

6.4 ERASE Pin

The ERASE pin is used to re-initialize the Flash content and some of its NVM bits. It integrates a permanent pull-down resistor of about 15 kΩ to GND.

To eliminate any risk of erasing the Flash due to noise on the ERASE pin, it shoul be tied externally to GND, which prevents erasing the Flash from the applicatiion, or pulled down with an external low-value resistor (such as 1 kΩ).

This pin is debounced by the RC oscillator to improve the glitch tolerance. Minimum debouncing time is 200 ms.

6.5 PIO Controller Lines

All the I/O lines, PA0 to PA30 and PB0 to PB30, are 5V-tolerant and all integrate a programmable pull-up resistor. Programming of this pull-up resistor is performed independently for each I/O line through the PIO controllers.

7. Processor and Architecture

7.1 ARM7TDMI Processor

- RISC processor based on ARMv4T Von Neumann architecture
  - Runs at up to 55 MHz, providing 0.9 MIPS/MHz
- Two instruction sets
  - ARM® high-performance 32-bit instruction set
  - Thumb® high code density 16-bit instruction set
- Three-stage pipeline architecture
  - Instruction Fetch (F)
  - Instruction Decode (D)
  - Execute (E)

7.2 Debug and Test Features

- Integrated embedded in-circuit emulator
  - Two watchpoint units
  - Test access port accessible through a JTAG protocol
  - Debug communication channel
- Debug Unit
  - Two-pin UART
  - Debug communication channel interrupt handling
  - Chip ID Register
- IEEE1149.1 JTAG Boundary-scan on all digital pins

7.3 Memory Controller

- Programmable Bus Arbiter
  - Handles requests from the ARM7TDMI, the Ethernet MAC and the Peripheral DMA Controller
- Address decoder provides selection signals for
  - Three internal 1 Mbyte memory areas
  - One 256 Mbyte embedded peripheral area
- Abort Status Registers
  - Source, Type and all parameters of the access leading to an abort are saved
  - Facilitates debug by detection of bad pointers
- Misalignment Detector
  - Alignment checking of all data accesses
  - Abort generation in case of misalignment
- Remap Command
  - Remaps the SRAM in place of the embedded non-volatile memory
  - Allows handling of dynamic exception vectors

8. Memory

8.1 AT91SAM7XC512

- 512 Kbytes of dual-plane Flash Memory
  - 2 contiguous banks of 1024 pages of 256 bytes
  - Fast access time, 30 MHz single-cycle access in Worst Case conditions
  - Page programming time: 6 ms, including page auto-erase
  - Page programming without auto-erase: 3 ms
  - Full chip erase time: 15 ms
  - 10,000 write cycles, 10-year data retention capability
  - 32 lock bits, protecting 32 sectors of 64 pages
  - Protection Mode to secure contents of the Flash
- 128 Kbytes of Fast SRAM
  - Single-cycle access at full speed

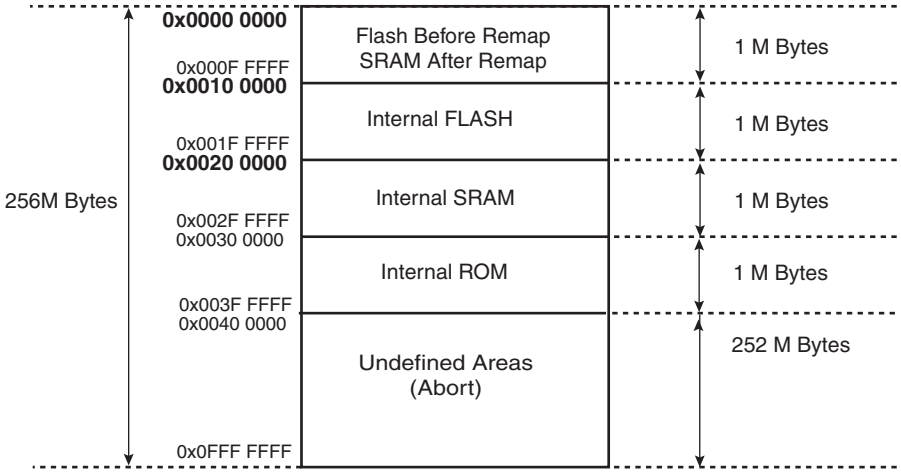
8.2 AT91SAM7XC256

- 256 Kbytes of Flash Memory
  - 1024 pages of 256 bytes
  - Fast access time, 30 MHz single-cycle access in Worst Case conditions
  - Page programming time: 6 ms, including page auto-erase
  - Page programming without auto-erase: 3 ms
  - Full chip erase time: 15 ms
  - 10,000 write cycles, 10-year data retention capability
  - 16 lock bits, each protecting 16 sectors of 64 pages
  - Protection Mode to secure contents of the Flash
- 64 Kbytes of Fast SRAM
  - Single-cycle access at full speed

8.3 AT91SAM7XC128

- 128 Kbytes of Flash Memory
  - 512 pages of 256 bytes
  - Fast access time, 30 MHz single-cycle access in Worst Case conditions
  - Page programming time: 6 ms, including page auto-erase
  - Page programming without auto-erase: 3 ms
  - Full chip erase time: 15 ms
  - 10,000 write cycles, 10-year data retention capability
  - 8 lock bits, each protecting 8 sectors of 64 pages
  - Protection Mode to secure contents of the Flash
- 32 Kbytes of Fast SRAM
  - Single-cycle access at full speed

Figure 8-3. Internal Memory Mapping with GPNVM Bit 2 = 1



8.5 Embedded Flash

8.5.1 Flash Overview

- The Flash of the AT91SAM7XC512 is organized in two banks (dual plane) 0f 1254 pages of 256 bytes. The 524, 288 bytes are organized in 32-bit words.
- The Flash of the AT91SAM7XC256 is organized in 1024 pages of 256 bytes (single plane). It reads as 65,536 32-bit words.
- The Flash of the AT91SAM7XC128 is organized in 512 pages of 256 bytes (single plane). It reads as 32,768 32-bit words.

The Flash contains a 256-byte write buffer, accessible through a 32-bit interface.

The Flash benefits from the integration of a power reset cell and from the brownout detector. This prevents code corruption during power supply changes, even in the worst conditions.

When Flash is not used (read or write access), it is automatically placed into standby mode.

8.5.2 Embedded Flash Controller

The Embedded Flash Controller (EFC) manages accesses performed by the masters of the system. It enables reading the Flash and writing the write buffer. It also contains a User Interface, mapped within the Memory Controller on the APB. The User Interface allows:

- programming of the access parameters of the Flash (number of wait states, timings, etc.)
- starting commands such as full erase, page erase, page program, NVM bit set, NVM bit clear, etc.
- getting the end status of the last command
- getting error status
- programming interrupts on the end of the last commands or on errors

The Embedded Flash Controller also provides a dual 32-bit Prefetch Buffer that optimizes 16-bit access to the Flash. This is particularly efficient when the processor is running in Thumb mode.

Two EFCs are embedded in the AT91SAM7XC512 to control each bank of 256 KBytes. Dual-plane organization allows concurrent read and program functionality. Read from one memory

plane may be performed even while program or erase functions are being executed in the other memory plane.

One EFC is embedded in the AT91SAM7XC256/128 to control the single plane of 256/128 KBytes.

8.5.3 Lock Regions

8.5.3.1 AT91SAM7XC512

Two Embedded Flash Controllers each manage 16 lock bits to protect 16 regions of the flash against inadvertent flash erasing or programming commands. The AT91SAM7XC512 contains 32 lock regions and each lock region contains 64 pages of 256 bytes. Each lock region has a size of 16 Kbytes.

If a locked-region's erase or program command occurs, the command is aborted and the EFC trigs an interrupt.

The 32 NVM bits are software programmable through both of the EFC User Interfaces. The command "Set Lock Bit" enables the protection. The command "Clear Lock Bit" unlocks the lock region.

Asserting the ERASE pin clears the lock bits, thus unlocking the entire Flash.

8.5.3.2 AT91SAM7XC256

The Embedded Flash Controller manages 16 lock bits to protect 16 regions of the flash against inadvertent flash erasing or programming commands. The AT91SAM7XC256 contains 16 lock regions and each lock region contains 64 pages of 256 bytes. Each lock region has a size of 16 Kbytes.

If a locked-region's erase or program command occurs, the command is aborted and the EFC trigs an interrupt.

The 16 NVM bits are software programmable through the EFC User Interface. The command "Set Lock Bit" enables the protection. The command "Clear Lock Bit" unlocks the lock region.

Asserting the ERASE pin clears the lock bits, thus unlocking the entire Flash.

8.5.3.3 AT91SAM7XC128

The Embedded Flash Controller manages 8 lock bits to protect 8 regions of the flash against inadvertent flash erasing or programming commands. The AT91SAM7XC128 contains 8 lock regions and each lock region contains 64 pages of 256 bytes. Each lock region has a size of 16 Kbytes.

If a locked-region's erase or program command occurs, the command is aborted and the EFC trigs an interrupt.

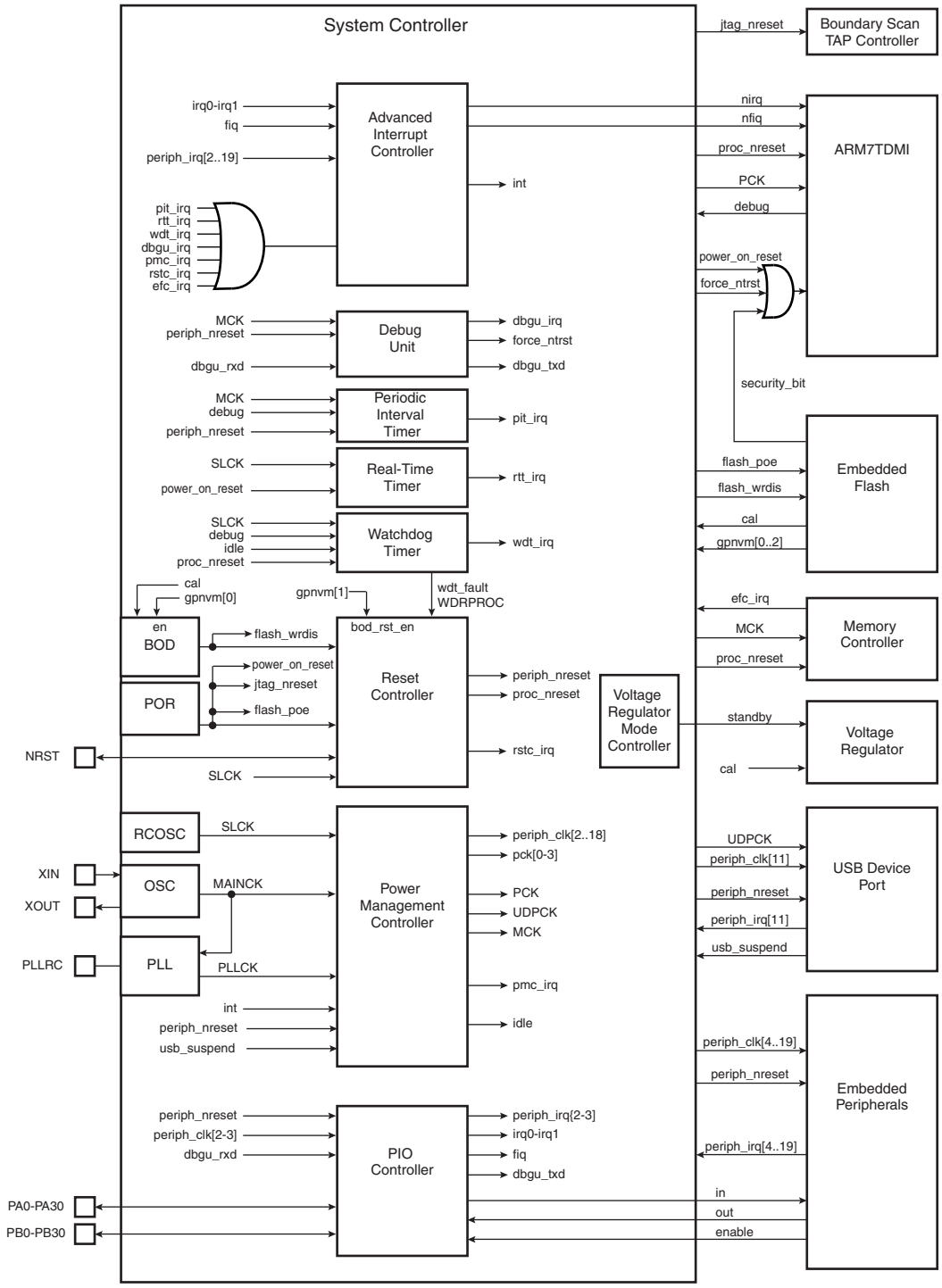
The 8 NVM bits are software programmable through the EFC User Interface. The command "Set Lock Bit" enables the protection. The command "Clear Lock Bit" unlocks the lock region.

Asserting the ERASE pin clears the lock bits, thus unlocking the entire Flash.

8.5.4 Security Bit Feature

The AT91SAM7XC512/256/128 features a security bit, based on a specific NVM-Bit. When the security is enabled, any access to the Flash, either through the ICE interface or through the Fast

Figure 9-1. System Controller Block Diagram



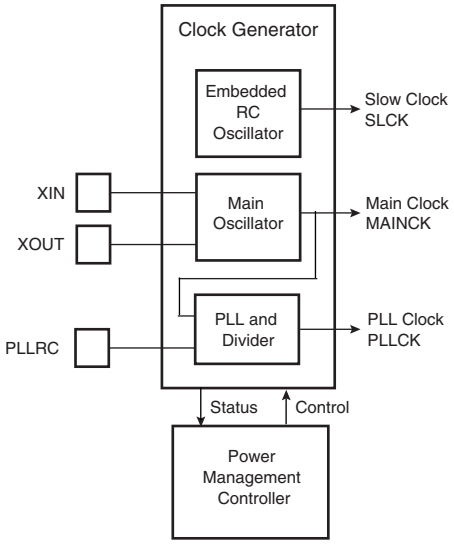
9.2 Clock Generator

The Clock Generator embeds one low-power RC Oscillator, one Main Oscillator and one PLL with the following characteristics:

- RC Oscillator ranges between 22 KHz and 42 KHz
- Main Oscillator frequency ranges between 3 and 20 MHz
- Main Oscillator can be bypassed
- PLL output ranges between 80 and 200 MHz

It provides SLCK, MAINCK and PLLCK.

Figure 9-2. Clock Generator Block Diagram



9.3 Power Management Controller

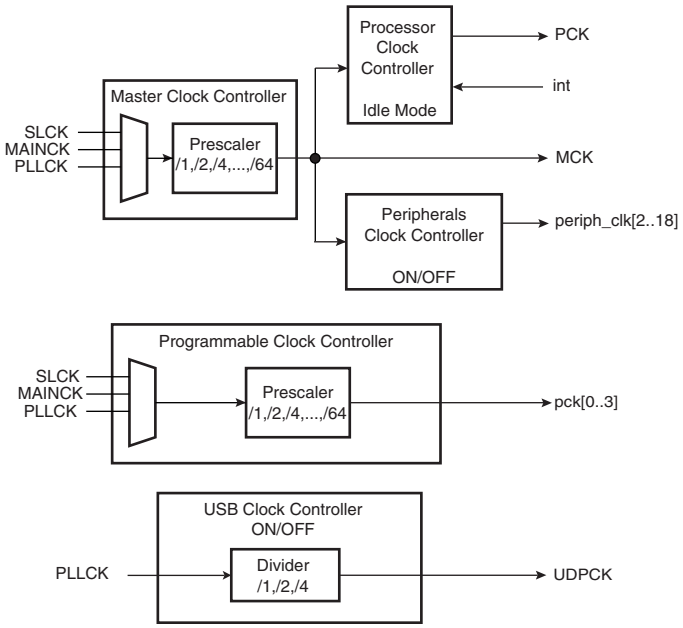
The Power Management Controller uses the Clock Generator outputs to provide:

- the Processor Clock PCK
- the Master Clock MCK
- the USB Clock UDPCK
- all the peripheral clocks, independently controllable
- four programmable clock outputs

The Master Clock (MCK) is programmable from a few hundred Hz to the maximum operating frequency of the device.

The Processor Clock (PCK) switches off when entering processor idle mode, thus allowing reduced power consumption while waiting for an interrupt.

Figure 9-3. Power Management Controller Block Diagram



9.4 Advanced Interrupt Controller

- Controls the interrupt lines (nIRQ and nFIQ) of an ARM Processor
- Individually maskable and vectored interrupt sources
  - Source 0 is reserved for the Fast Interrupt Input (FIQ)
  - Source 1 is reserved for system peripherals (RTT, PIT, EFC, PMC, DBGU, etc.)
  - Other sources control the peripheral interrupts or external interrupts
  - Programmable edge-triggered or level-sensitive internal sources
  - Programmable positive/negative edge-triggered or high/low level-sensitive external sources
- 8-level Priority Controller
  - Drives the normal interrupt nIRQ of the processor
  - Handles priority of the interrupt sources

- Programmable 16-bit prescaler for SLCK accuracy compensation

9.9 PIO Controllers

- Two PIO Controllers, each controlling 31 I/O lines
- Fully programmable through set/clear registers
- Multiplexing of two peripheral functions per I/O line
- For each I/O line (whether assigned to a peripheral or used as general-purpose I/O)
  - Input change interrupt
  - Half a clock period glitch filter
  - Multi-drive option enables driving in open drain
  - Programmable pull-up on each I/O line
  - Pin data status register, supplies visibility of the level on the pin at any time
- Synchronous output, provides Set and Clear of several I/O lines in a single write

9.10 Voltage Regulator Controller

The purpose of this controller is to select the Power Mode of the Voltage Regulator between Normal Mode (bit 0 is cleared) or Standby Mode (bit 0 is set).

10.3 Peripheral Multiplexing on PIO Lines

The AT91SAM7XC512/256/128 features two PIO controllers, PIOA and PIOB, that multiplex the I/O lines of the peripheral set.

Each PIO Controller controls 31 lines. Each line can be assigned to one of two peripheral functions, A or B. Some of them can also be multiplexed with the analog inputs of the ADC Controller.

Table 10-2 on page 34 and Table 10-3 on page 35 defines how the I/O lines of the peripherals A, B or the analog inputs are multiplexed on the PIO Controller A and PIO Controller B. The two columns “Function” and “Comments” have been inserted for the user’s own comments; they may be used to track how pins are defined in an application.

Note that some peripheral functions that are output only, may be duplicated in the table.

At reset, all I/O lines are automatically configured as input with the programmable pull-up enabled, so that the device is maintained in a static state as soon as a reset is detected.

10.5 PIO Controller B Multiplexing

Table 10-3. Multiplexing on PIO Controller B

PIO Controller B				Application Usage	
I/O Line	Peripheral A	Peripheral B	Comments	Function	Comments
PB0	ETXCK/EREFCK	PCK0			
PB1	ETXEN				
PB2	ETX0				
PB3	ETX1				
PB4	ECRS				
PB5	ERX0				
PB6	ERX1				
PB7	ERXER				
PB8	EMDC				
PB9	EMDIO				
PB10	ETX2	SPI1_NPCS1			
PB11	ETX3	SPI1_NPCS2			
PB12	ETXER	TCLK0			
PB13	ERX2	SPI0_NPCS1			
PB14	ERX3	SPI0_NPCS2			
PB15	ERXDV/ECRSDV				
PB16	ECOL	SPI1_NPCS3			
PB17	ERXCK	SPI0_NPCS3			
PB18	EF100	ADTRG			
PB19	PWM0	TCLK1			
PB20	PWM1	PCK0			
PB21	PWM2	PCK1			
PB22	PWM3	PCK2			
PB23	TIOA0	DCD1			
PB24	TIOB0	DSR1			
PB25	TIOA1	DTR1			
PB26	TIOB1	RI1			
PB27	TIOA2	PWM0	AD0		
PB28	TIOB2	PWM1	AD1		
PB29	PCK1	PWM2	AD2		
PB30	PCK2	PWM3	AD3		

  - Automatic wakeup on trigger and back to sleep mode after conversions of all enabled channels
- Four of eight analog inputs shared with digital signals

11. Package Drawings

Figure 11-1. LQFP Package Drawing

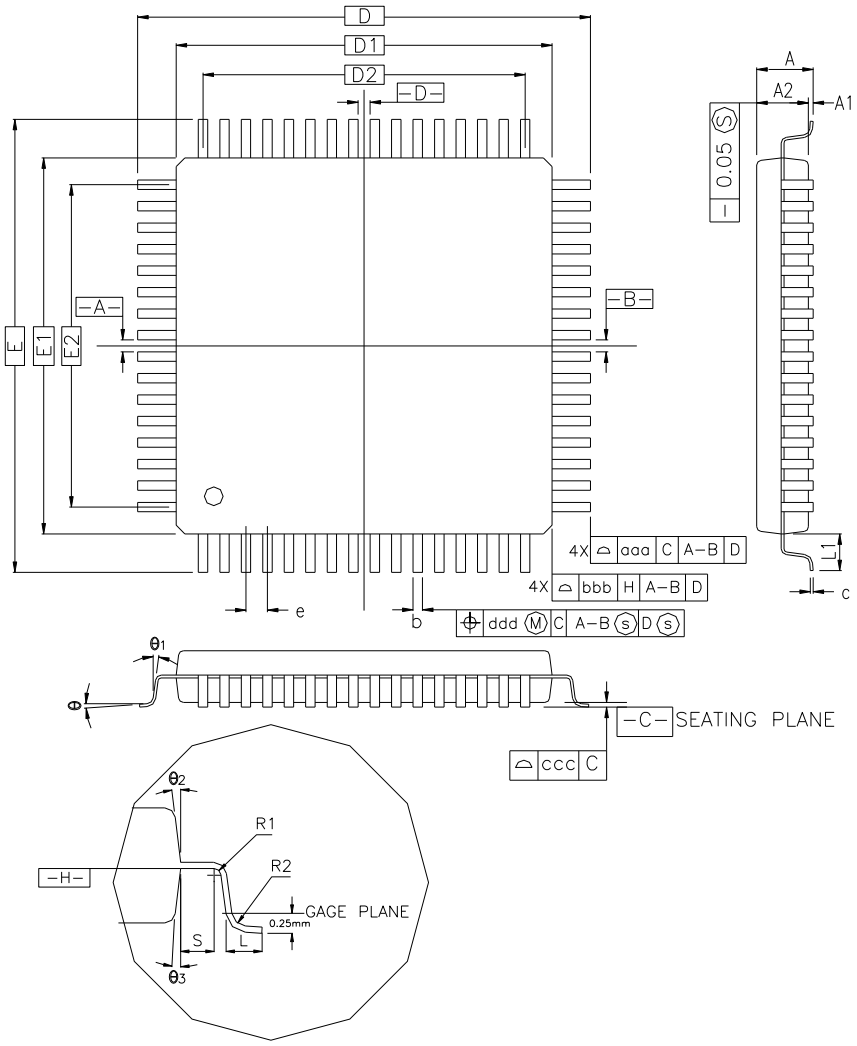
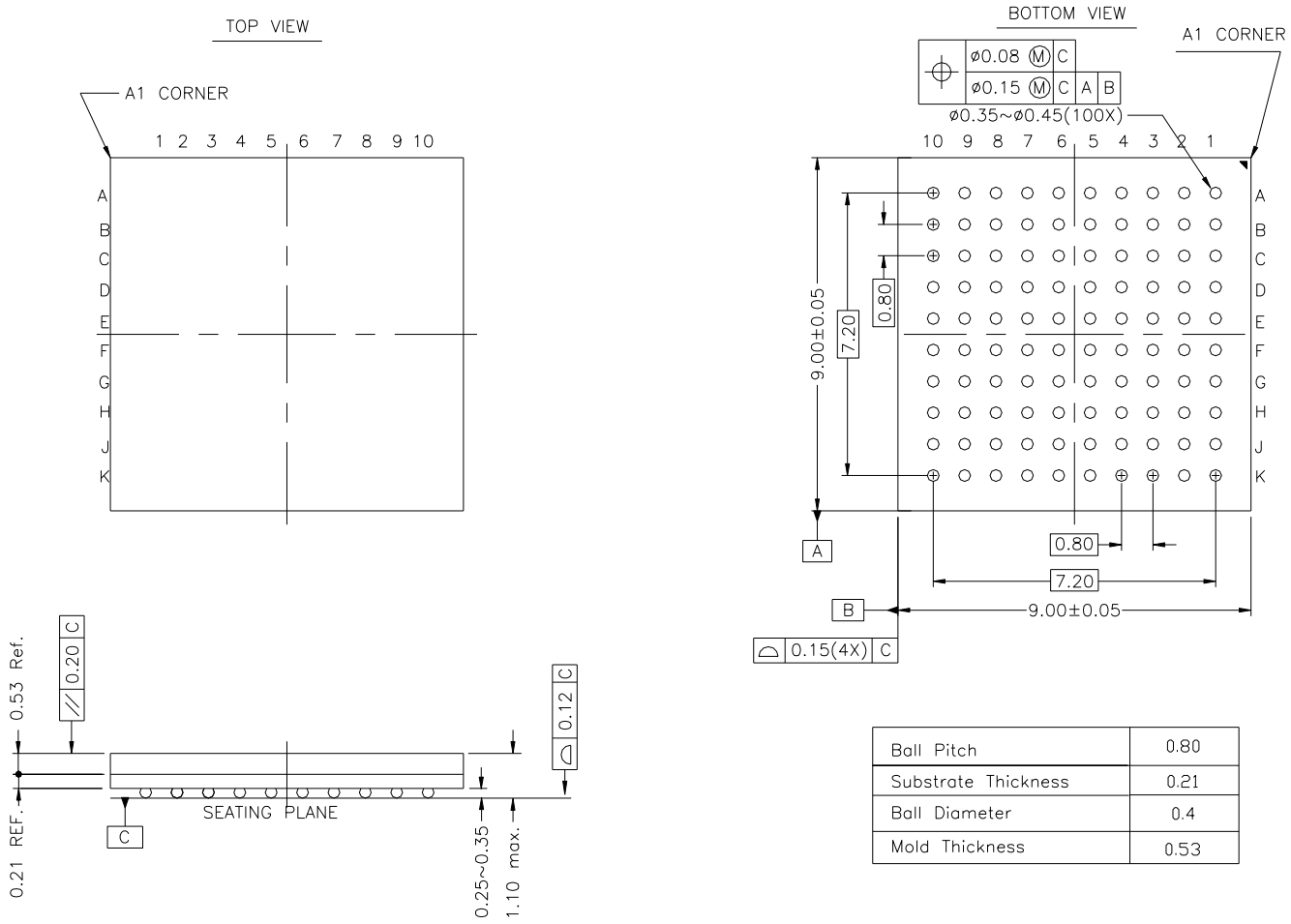


Table 11-1. 100-lead LQFP Package Dimensions

Symbol	Millimeter			Inch		
	Min	Nom	Max	Min	Nom	Max
A			1.60			0.63
A1	0.05		0.15	0.002		0.006
A2	1.35	1.40	1.45	0.053	0.055	0.057
D		16.00 BSC			0.630 BSC	
D1		14.00 BSC			0.551 BSC	
E		16.00 BSC			0.630 BSC	
E1		14.00 BSC			0.551 BSC	
R2	0.08		0.20	0.003		0.008
R1	0.08			0.003		
Q	0·	3.5·	7·	0·	3.5·	7·
θ1	0·			0·		
θ2	11·	12·	13·	11·	12·	13·
θ3	11·	12·	13·	11·	12·	13·
c	0.09		0.20	0.004		0.008
L	0.45	0.60	0.75	0.018	0.024	0.030
L1		1.00 REF			0.039 REF	
S	0.20			0.008		
b	0.17	0.20	0.27	0.007	0.008	0.011
e		0.50 BSC			0.020 BSC	
D2		12.00			0.472	
E2		12.00			0.472	
Tolerances of Form and Position						
aaa		0.20			0.008	
bbb		0.20			0.008	
ccc		0.08			0.003	
ddd		0.08			0.003	

Figure 11-2. 100-TFBGA Package Drawing



Ball Pitch	0.80
Substrate Thickness	0.21
Ball Diameter	0.4
Mold Thickness	0.53

All dimensions are in mm

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